

Absolute Maximum Ratings		$T_s = 25^\circ\text{C}$, unless otherwise specified		
Symbol	Conditions	Values		Units
MOSFET				
V_{DSS}		55		V
V_{GSS}		± 20		V
I_D	$T_s = 25 \text{ (80)}^\circ\text{C}; 1$	240 (150)	A	
I_{DM}	$t_p < 1 \text{ ms}; T_s = 25 \text{ (80)}^\circ\text{C}; 1$	340 (250)	A	
T_j		-40...+150		$^\circ\text{C}$
Inverse diode				
$I_F = -I_D$	$T_s = 25 \text{ (80)}^\circ\text{C};$	240 (150)	A	
$I_{FM} = -I_{DM}$	$t_p < 1 \text{ ms}; T_s = 25 \text{ (80)}^\circ\text{C};$	340 (250)	A	
T_j		-40...+150		$^\circ\text{C}$
Freewheeling CAL diode				
$I_F = -I_D$	$T_s = 25^\circ\text{C}$	160	A	
T_j			$^\circ\text{C}$	
T_{stg}		-40 ... +125	$^\circ\text{C}$	
T_{sol}	Terminals, 10 s	260	$^\circ\text{C}$	
V_{isol}	AC, 1 min (1s)	2500 / 3000	V	

Mosfet Module

SK 150 MBL 055 T

Target Data

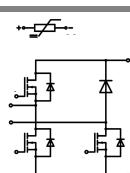
Features

- Compact design
- One screw mounting
- Heat transfer and isolation through direct copper bonded aluminium oxide ceramic (DCB)
- Trench technology
- Short internal connections and low inductance case
- Integrated PTC temperature sensor

Typical Applications

- Low switched mode power supplies
 - DC servo drives
 - UPS
- 1) Maximum PCB temperature, at pins/PCB contact, = 85°C

Characteristics		$T_s = 25^\circ\text{C}$, unless otherwise specified		
Symbol	Conditions	min.	typ.	max.
MOSFET				
$V_{(BR)DSS}$	$V_{GS} = 0 \text{ V}, I_D = 0,25 \text{ mA}$	55		V
$V_{GS(th)}$	$V_{GS} = V_{DS}; I_D = 0,25 \text{ mA}$	2,5	3,2	V
I_{DSS}	$V_{GS} = 0 \text{ V}; V_{DS} = V_{DSS}; T_j = 25 \text{ (125)}^\circ\text{C}$		1	μA
I_{GSS}	$V_{GS} = \pm 20 \text{ V}; V_{DS} = 0 \text{ V}$		100	nA
$R_{DS(on)}$	$I_D = 5 \text{ A}; V_{GS} = 10 \text{ V}; T_j = 25^\circ\text{C}$		1,1	$\text{m}\Omega$
$R_{DS(on)}$	$I_D = 5 \text{ A}; V_{GS} = 10 \text{ V}; T_j = 125^\circ\text{C}$		1,9	$\text{m}\Omega$
C_{CHC}	per MOSFET			pF
C_{iss}	under following conditions: $V_{GS} = 0 \text{ V}; V_{DS} = 25 \text{ V}; f = 1 \text{ MHz}$	21,2		nF
C_{oss}		3,3		nF
C_{rss}		1,6		nF
L_{DS}				nH
$t_{d(on)}$	under following conditions: $V_{DD} = 30 \text{ V}; V_{GS} = 10 \text{ V};$	40		ns
t_f	$I_D = 70 \text{ A}$	180		ns
$t_{d(off)}$	$R_G = 2,5 \Omega$	70		ns
t_f		110		ns
$R_{th(j-s)}$	per MOSFET (per module)		0,8	K/W
Inverse diode				
V_{SD}	$I_F = 5 \text{ A}; V_{GS} = 0 \text{ V}; T_j = 25^\circ\text{C}$	0,7	1,5	V
I_{RRM}	under following conditions:	8		A
Q_{rr}	$I_F = 150 \text{ A}; T_{vj} = 25^\circ\text{C}; R_G = 2,5 \Omega$	0,35		μC
t_{rr}	$V_R = 30 \text{ A}; \text{di}/\text{dt} = 100 \text{ A}/\mu\text{s}$	80		ns
Free-wheeling diode				
V_F	$I_F = 100 \text{ A}; V_{GS} = V$	0,75		V
$R_{th(j-s)}$	Per diode		0,75	K/W
I_{RRM}	under following conditions:			A
Q_{rr}	$I_F = 150 \text{ A}; T_{vj} = 25^\circ\text{C}$			μC
t_{rr}	$V_r = 60 \text{ A}; \text{di}/\text{dt} = 100 \text{ A}/\mu\text{s}$			ns
Mechanical data				
M1	mounting torque		2,5	Nm
w		30		g
Case	SEMITOP® 3	T 65		



MBL

SK 150 MBL 055 T MOSFET, TRANSISTOR

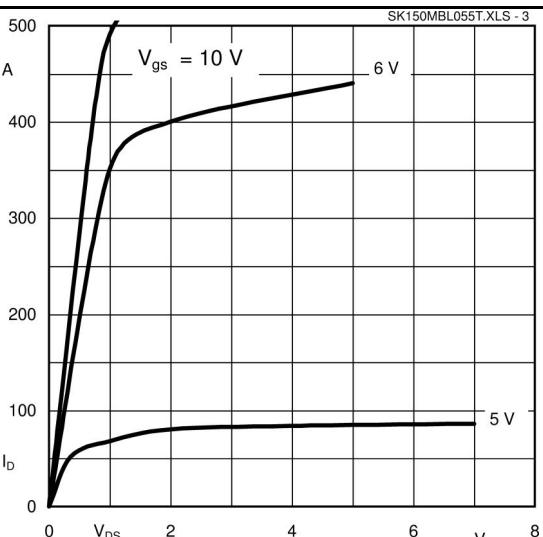


Fig. 3 Output characteristic, $t_p = 80\text{ }\mu\text{s}$, $T_j = 25^\circ\text{C}$

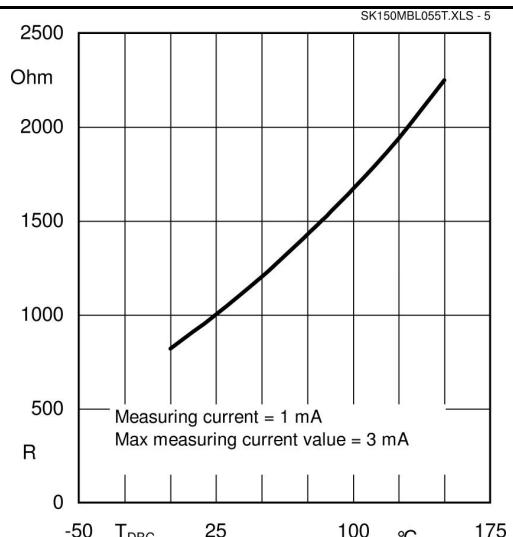


Fig. 4 Typ. PTC Characteristic

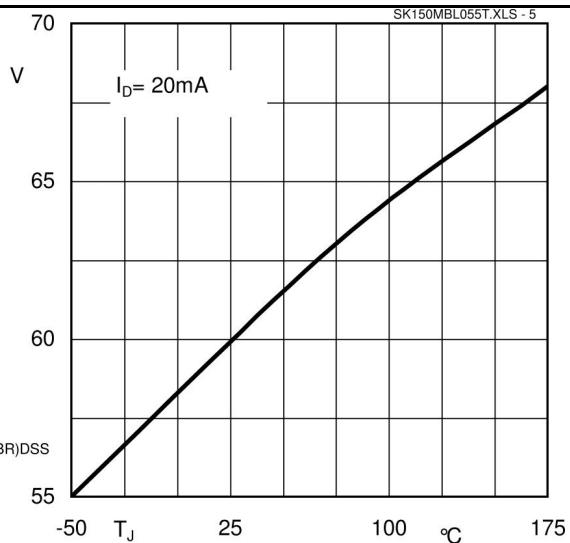


Fig. 5 Breakdown voltage vs. temperature

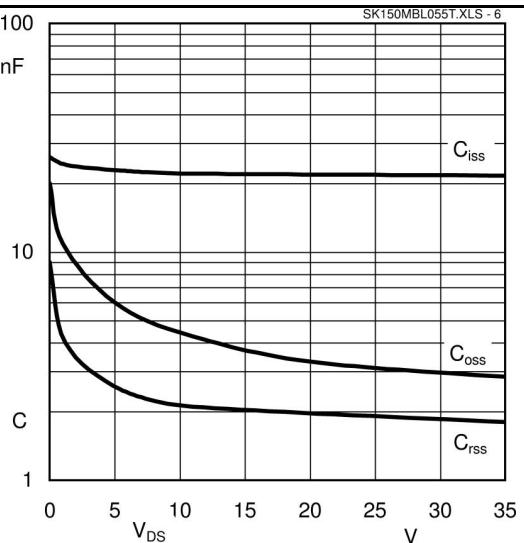


Fig. 6 Typ. capacitancies vs. drain-source voltage

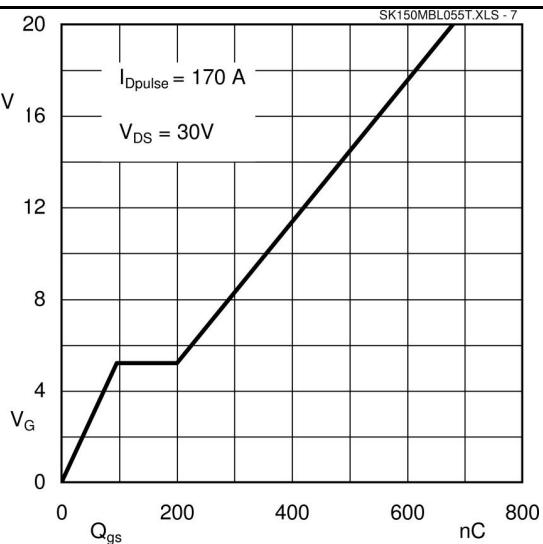


Fig. 7 Gate charge characteristic

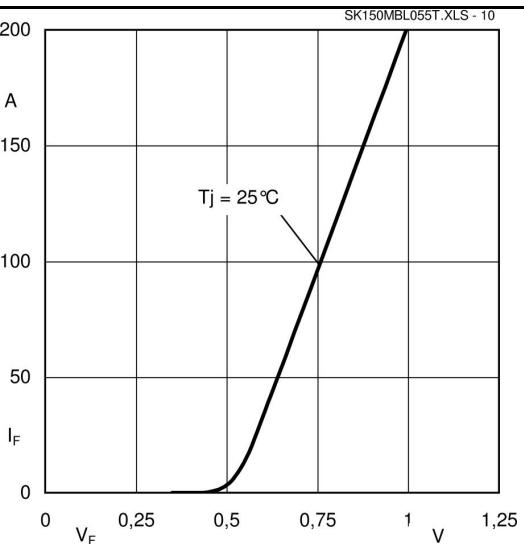
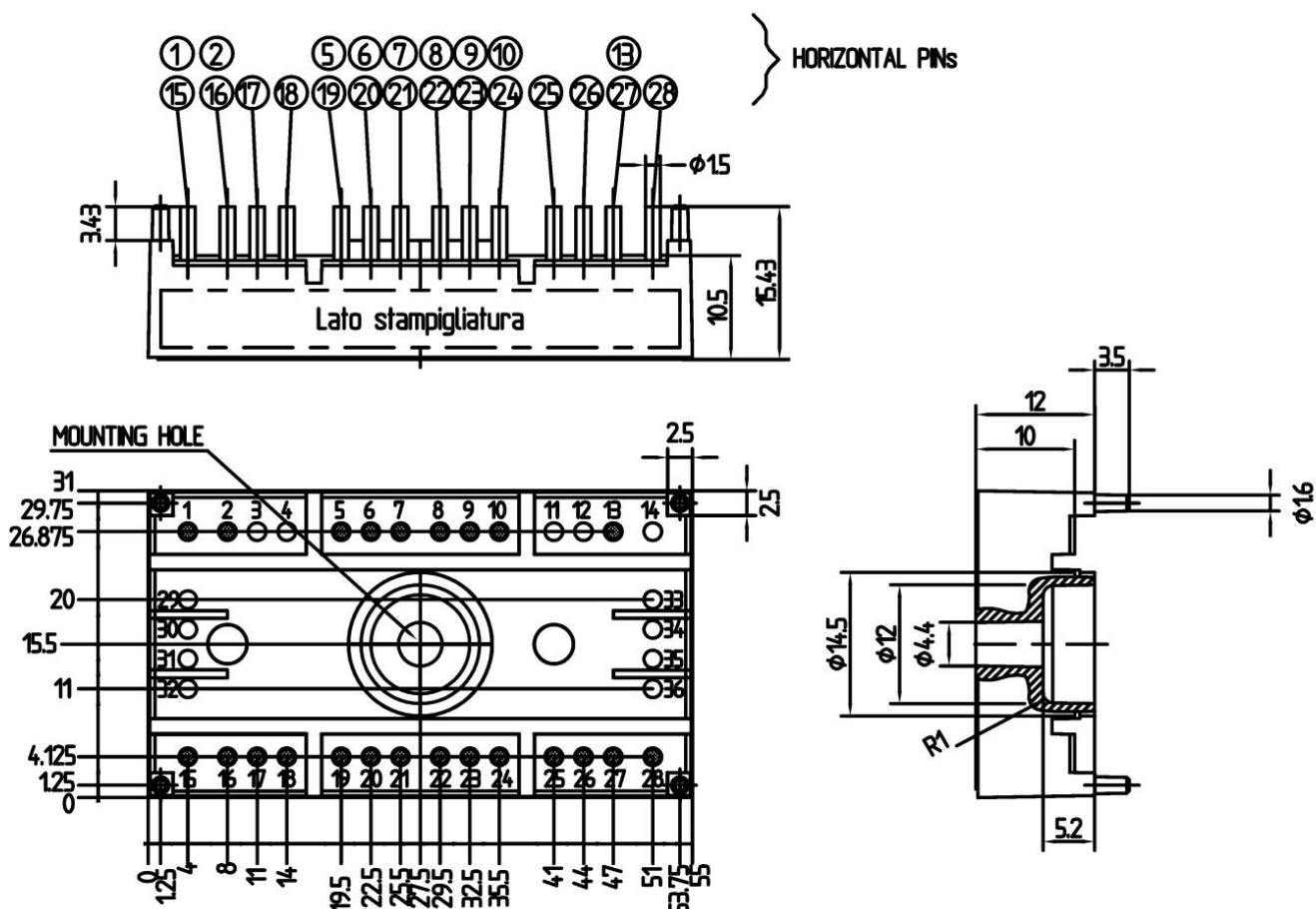
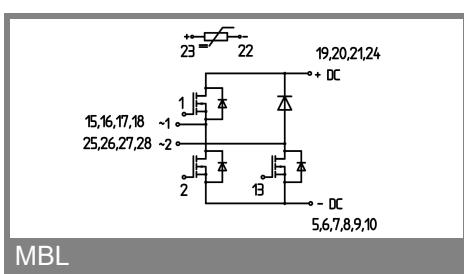


Fig. 10 FWD forward characteristic, $t_p = 80\text{ }\mu\text{s}$

Dimensions in mm



Case T65



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